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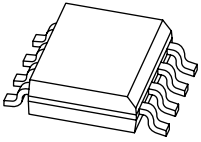
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# PBSS4021SPN

20 V NPN/PNP low  $V_{CEsat}$  (BISS) transistor

Rev. 2 — 13 October 2010

Product data sheet

## 1. Product profile

### 1.1 General description

NPN/PNP low  $V_{CEsat}$  Breakthrough In Small Signal (BISS) transistor in a SOT96-1 (SO8) medium power Surface-Mounted Device (SMD) plastic package.

Table 1. Product overview

| Type number | Package |      | NPN/PNP complement | PNP/PNP complement |
|-------------|---------|------|--------------------|--------------------|
|             | NXP     | Name |                    |                    |
| PBSS4021SPN | SOT96-1 | SO8  | PBSS4021SN         | PBSS4021SP         |

### 1.2 Features and benefits

- Very low collector-emitter saturation voltage  $V_{CEsat}$
- High collector current capability  $I_C$  and  $I_{CM}$
- High collector current gain ( $h_{FE}$ ) at high  $I_C$
- High efficiency due to less heat generation
- Smaller required Printed-Circuit Board (PCB) area than for conventional transistors

### 1.3 Applications

- Loadswitch
- Battery-driven devices
- Power management
- Charging circuits
- Power switches (e.g. motors, fans)

### 1.4 Quick reference data

Table 2. Quick reference data

| Symbol  | Parameter                               | Conditions                    | Min                   | Typ | Max | Unit       |
|---|---|-------------------------------|-----------------------|-----|-----|------------|
| <b>TR1; NPN low <math>V_{CEsat}</math> transistor</b> |   |                               |                       |     |     |            |
| $V_{CEO}$   | collector-emitter voltage               | open base                     | -                     | -   | 20  | V          |
| $I_C$   | collector current                       |                               | -                     | -   | 7.5 | A          |
| $I_{CM}$  | peak collector current                  | single pulse; $t_p \leq 1$ ms | -                     | -   | 15  | A          |
| $R_{CEsat}$   | collector-emitter saturation resistance | $I_C = 5$ A; $I_B = 0.5$ A    | <a href="#">[1]</a> - | 25  | 35  | m $\Omega$ |



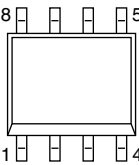
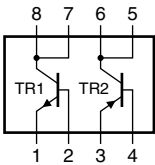
**Table 2. Quick reference data ...continued**

| Symbol  | Parameter                               | Conditions                       | Min | Typ | Max  | Unit       |
|---|---|----------------------------------|-----|-----|------|------------|
| <b>TR2; PNP low <math>V_{CEsat}</math> transistor</b> |   |                                  |     |     |      |            |
| $V_{CEO}$   | collector-emitter voltage               | open base                        | -   | -   | -20  | V          |
| $I_C$   | collector current                       |                                  | -   | -   | -6.3 | A          |
| $I_{CM}$  | peak collector current                  | single pulse; $t_p \leq 1$ ms    | -   | -   | -15  | A          |
| $R_{CEsat}$   | collector-emitter saturation resistance | $I_C = -5$ A; $I_B = -0.5$ A [1] | -   | 36  | 54   | m $\Omega$ |

[1] Pulse test:  $t_p \leq 300$   $\mu$ s;  $\delta \leq 0.02$ .

## 2. Pinning information

**Table 3. Pinning**

| Pin | Description   | Simplified outline   | Graphic symbol   |
|-----|---------------|--|--|
| 1   | emitter TR1   |  |  |
| 2   | base TR1      |  |  |
| 3   | emitter TR2   |  |  |
| 4   | base TR2      |  |  |
| 5   | collector TR2 |  |  |
| 6   | collector TR2 |  |  |
| 7   | collector TR1 |  |  |
| 8   | collector TR1 |  |  |

## 3. Ordering information

**Table 4. Ordering information**

| Type number | Package |   | Version |
|-------------|---------|---|---------|
|             | Name    | Description   |         |
| PBSS4021SPN | SO8     | plastic small outline package; 8 leads; body width 3.9 mm | SOT96-1 |

## 4. Marking

**Table 5. Marking codes**

| Type number | Marking code |
|-------------|--------------|
| PBSS4021SPN | 4021SPN      |

## 5. Limiting values

**Table 6. Limiting values**

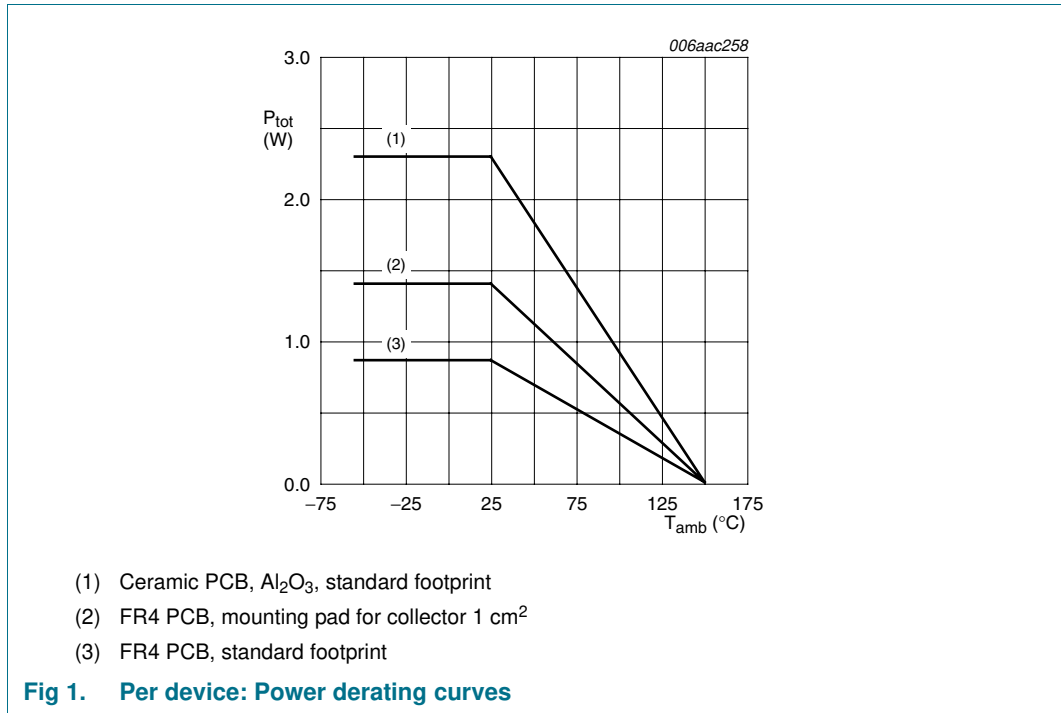
*In accordance with the Absolute Maximum Rating System (IEC 60134).*

| Symbol   | Parameter                 | Conditions                    | Min | Max  | Unit |   |
|--|---------------------------|-------------------------------|-----|------|------|---|
| <b>TR1 (NPN)</b>   |                           |                               |     |      |      |   |
| $I_C$  | collector current         |                               | -   | 7.5  | A    |   |
| <b>TR2 (PNP)</b>   |                           |                               |     |      |      |   |
| $I_C$  | collector current         |                               | -   | -6.3 | A    |   |
| <b>Per transistor; for the PNP transistor with negative polarity</b> |                           |                               |     |      |      |   |
| $V_{CBO}$  | collector-base voltage    | open emitter                  | -   | 20   | V    |   |
| $V_{CEO}$  | collector-emitter voltage | open base                     | -   | 20   | V    |   |
| $V_{EBO}$  | emitter-base voltage      | open collector                | -   | 5    | V    |   |
| $I_{CM}$   | peak collector current    | single pulse; $t_p \leq 1$ ms | -   | 15   | A    |   |
| $I_B$  | base current              |                               | -   | 1    | A    |   |
| $P_{tot}$  | total power dissipation   | $T_{amb} \leq 25$ °C          | [1] | -    | 0.73 | W |
|  |                           |                               | [2] | -    | 1    | W |
|  |                           |                               | [3] | -    | 1.7  | W |
| <b>Per device</b>  |                           |                               |     |      |      |   |
| $P_{tot}$  | total power dissipation   | $T_{amb} \leq 25$ °C          | [1] | -    | 0.86 | W |
|  |                           |                               | [2] | -    | 1.4  | W |
|  |                           |                               | [3] | -    | 2.3  | W |
| $T_j$  | junction temperature      |                               | -   | 150  | °C   |   |
| $T_{amb}$  | ambient temperature       |                               | -55 | +150 | °C   |   |
| $T_{stg}$  | storage temperature       |                               | -65 | +150 | °C   |   |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.

[3] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.



## 6. Thermal characteristics

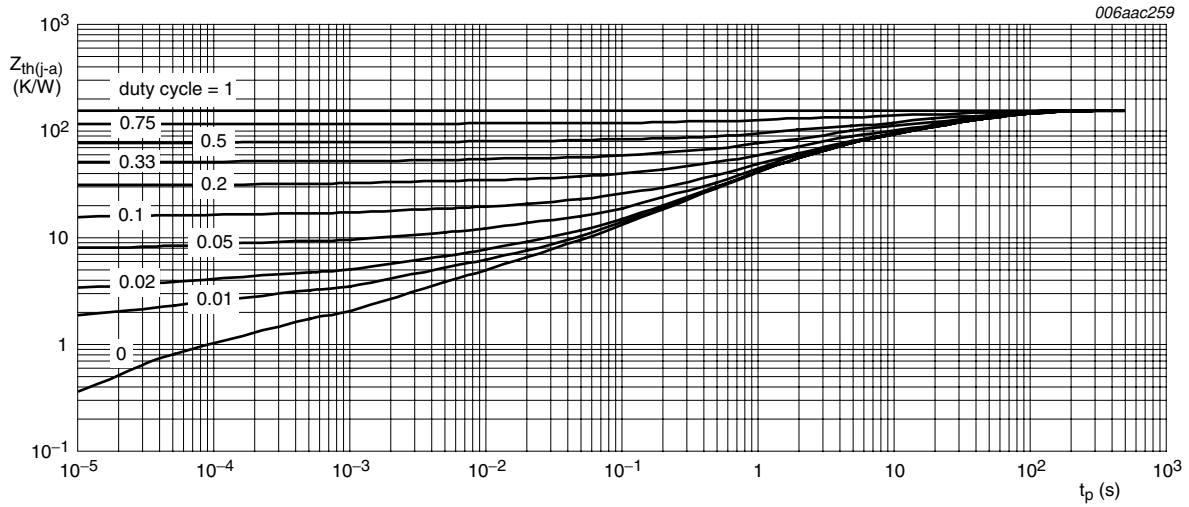
**Table 7. Thermal characteristics**

| Symbol                | Parameter  | Conditions  | Min | Typ | Max | Unit |     |
|-----------------------|--|-------------|-----|-----|-----|------|-----|
| <b>Per transistor</b> |  |             |     |     |     |      |     |
| R <sub>th(j-a)</sub>  | thermal resistance from junction to ambient      | in free air | [1] | -   | -   | 170  | K/W |
|                       |  |             | [2] | -   | -   | 125  | K/W |
|                       |  |             | [3] | -   | -   | 75   | K/W |
| R <sub>th(j-sp)</sub> | thermal resistance from junction to solder point |             | -   | -   | 40  | K/W  |     |
| <b>Per device</b>     |  |             |     |     |     |      |     |
| R <sub>th(j-a)</sub>  | thermal resistance from junction to ambient      | in free air | [1] | -   | -   | 145  | K/W |
|                       |  |             | [2] | -   | -   | 90   | K/W |
|                       |  |             | [3] | -   | -   | 55   | K/W |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

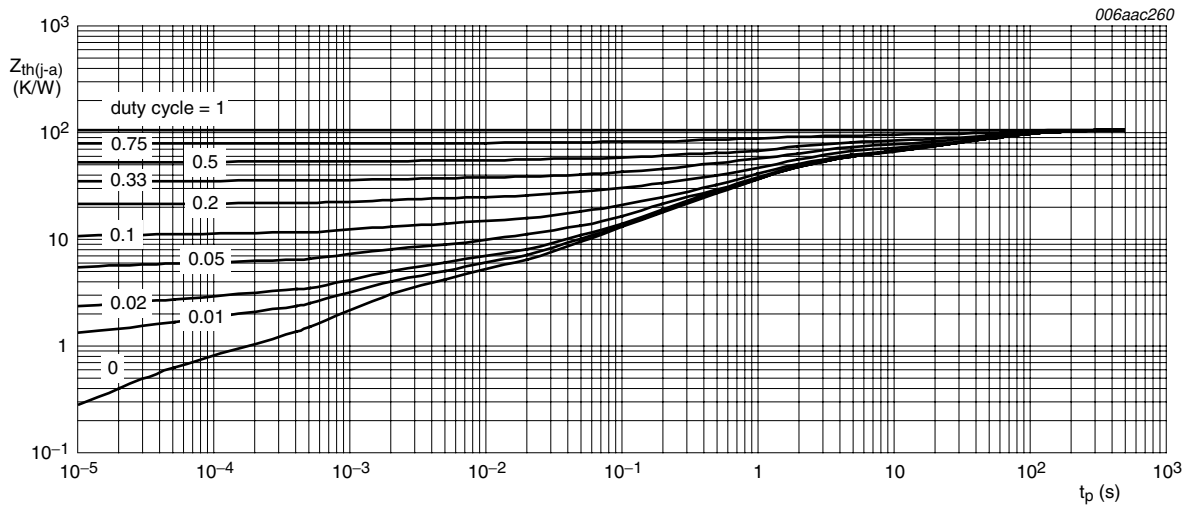
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm<sup>2</sup>.

[3] Device mounted on a ceramic PCB, Al<sub>2</sub>O<sub>3</sub>, standard footprint.



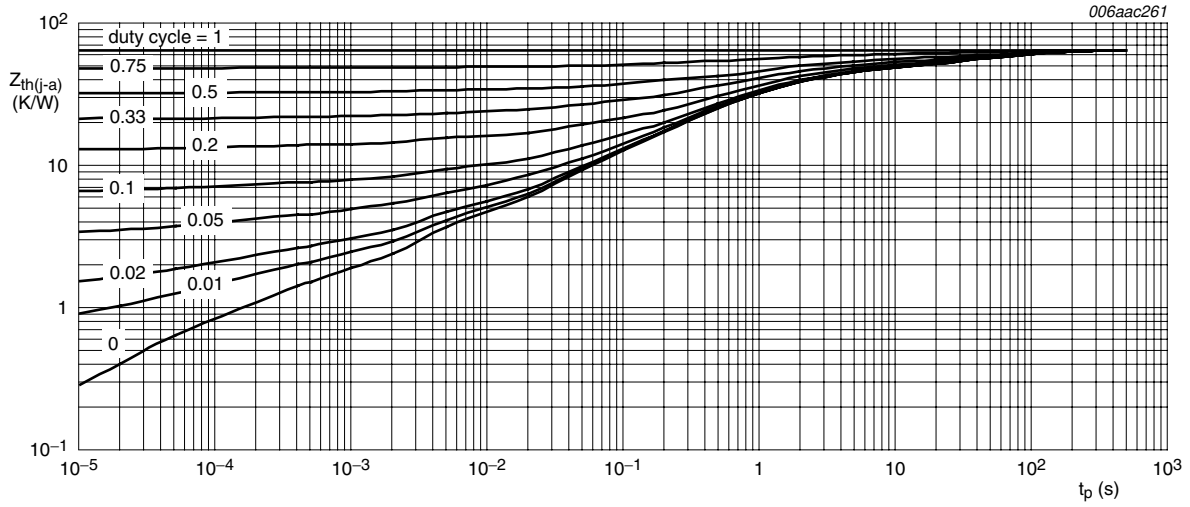
FR4 PCB, standard footprint

**Fig 2. Per transistor: Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**



FR4 PCB, mounting pad for collector 1 cm<sup>2</sup>

**Fig 3. Per transistor: Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**



Ceramic PCB,  $Al_2O_3$ , standard footprint

**Fig 4. Per transistor: Transient thermal impedance from junction to ambient as a function of pulse duration; typical values**



## 7. Characteristics

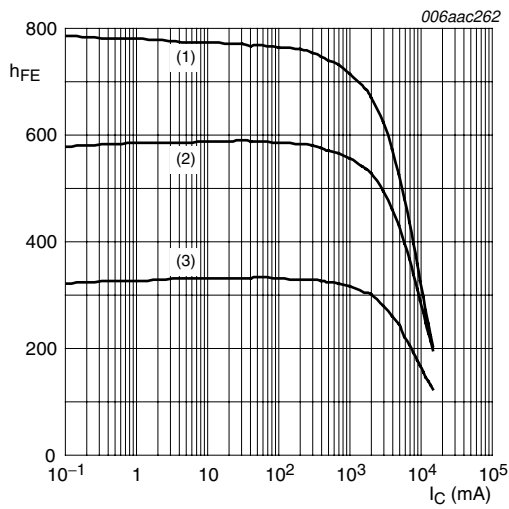
**Table 8. Characteristics**
 $T_{amb} = 25\text{ °C}$  unless otherwise specified.

| Symbol  | Parameter                               | Conditions   | Min | Typ  | Max  | Unit          |                  |
|---|---|--|-----|------|------|---------------|------------------|
| <b>TR1; NPN low <math>V_{CEsat}</math> transistor</b> |   |  |     |      |      |               |                  |
| $I_{CBO}$   | collector-base cut-off current          | $V_{CB} = 20\text{ V}; I_E = 0\text{ A}$   | -   | -    | 100  | nA            |                  |
|   |   | $V_{CB} = 20\text{ V}; I_E = 0\text{ A}; T_j = 150\text{ °C}$                                  | -   | -    | 50   | $\mu\text{A}$ |                  |
| $I_{CES}$   | collector-emitter cut-off current       | $V_{CE} = 16\text{ V}; V_{BE} = 0\text{ V}$  | -   | -    | 100  | nA            |                  |
| $I_{EBO}$   | emitter-base cut-off current            | $V_{EB} = 5\text{ V}; I_C = 0\text{ A}$  | -   | -    | 100  | nA            |                  |
| $h_{FE}$  | DC current gain                         | $V_{CE} = 2\text{ V}$  | [1] |      |      |               |                  |
|   |   | $I_C = 500\text{ mA}$  | 300 | 550  | -    |               |                  |
|   |   | $I_C = 1\text{ A}$   | 300 | 550  | -    |               |                  |
|   |   | $I_C = 2\text{ A}$   | 300 | 500  | -    |               |                  |
|   |   | $I_C = 4\text{ A}$   | 250 | 450  | -    |               |                  |
|   |   | $I_C = 8\text{ A}$   | 100 | 200  | -    |               |                  |
| $V_{CEsat}$   | collector-emitter saturation voltage    | [1]  |     |      |      |               |                  |
|   |   | $I_C = 1\text{ A}; I_B = 50\text{ mA}$   | -   | 30   | 45   | mV            |                  |
|   |   | $I_C = 1\text{ A}; I_B = 10\text{ mA}$   | -   | 40   | 60   | mV            |                  |
|   |   | $I_C = 2\text{ A}; I_B = 40\text{ mA}$   | -   | 60   | 90   | mV            |                  |
|   |   | $I_C = 4\text{ A}; I_B = 200\text{ mA}$  | -   | 100  | 150  | mV            |                  |
|   |   | $I_C = 4\text{ A}; I_B = 40\text{ mA}$   | -   | 120  | 180  | mV            |                  |
| $R_{CEsat}$   | collector-emitter saturation resistance | $I_C = 5\text{ A}; I_B = 500\text{ mA}$  | [1] | -    | 25   | 35            | $\text{m}\Omega$ |
|   |   |  |     |      |      |               |                  |
| $V_{BEsat}$   | base-emitter saturation voltage         | [1]  |     |      |      |               |                  |
|   |   | $I_C = 1\text{ A}; I_B = 100\text{ mA}$  | -   | 0.87 | 1    | V             |                  |
|   |   | $I_C = 4\text{ A}; I_B = 400\text{ mA}$  | -   | 1.04 | 1.2  | V             |                  |
| $V_{BEon}$  | base-emitter turn-on voltage            | $V_{CE} = 2\text{ V}; I_C = 2\text{ A}$  | [1] | -    | 0.76 | 0.85          | V                |
| $t_d$   | delay time                              | $V_{CC} = 12.5\text{ V}; I_C = 1\text{ A}; I_{Bon} = 0.05\text{ A}; I_{Boff} = -0.05\text{ A}$ | -   | 40   | -    | ns            |                  |
| $t_r$   | rise time                               |  | -   | 40   | -    | ns            |                  |
| $t_{on}$  | turn-on time                            |  | -   | 80   | -    | ns            |                  |
| $t_s$   | storage time                            |  | -   | 650  | -    | ns            |                  |
| $t_f$   | fall time                               |  | -   | 75   | -    | ns            |                  |
| $t_{off}$   | turn-off time                           |  | -   | 725  | -    | ns            |                  |
| $f_T$   | transition frequency                    | $V_{CE} = 10\text{ V}; I_C = 100\text{ mA}; f = 100\text{ MHz}$                                | -   | 115  | -    | MHz           |                  |
| $C_C$   | collector capacitance                   | $V_{CB} = 10\text{ V}; I_E = I_e = 0\text{ A}; f = 1\text{ MHz}$                               | -   | 85   | -    | pF            |                  |

**Table 8. Characteristics ...continued**  
 $T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

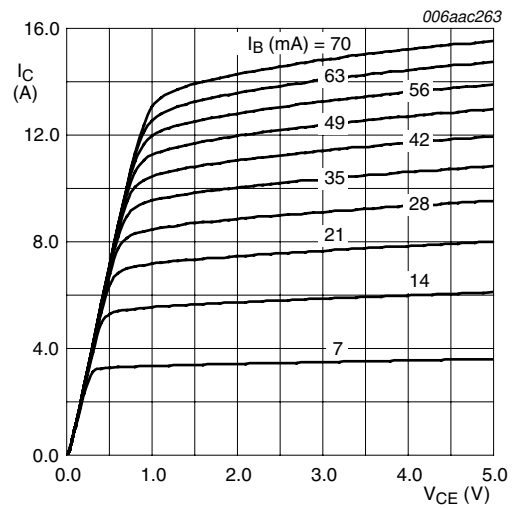
| Symbol  | Parameter                               | Conditions   | Min | Typ   | Max   | Unit          |                  |
|---|---|--|-----|-------|-------|---------------|------------------|
| <b>TR2; PNP low <math>V_{CEsat}</math> transistor</b> |   |  |     |       |       |               |                  |
| $I_{CBO}$   | collector-base cut-off current          | $V_{CB} = -20\text{ V}; I_E = 0\text{ A}$  | -   | -     | -100  | nA            |                  |
|   |   | $V_{CB} = -20\text{ V}; I_E = 0\text{ A}; T_j = 150\text{ }^{\circ}\text{C}$                     | -   | -     | -50   | $\mu\text{A}$ |                  |
| $I_{CES}$   | collector-emitter cut-off current       | $V_{CE} = -16\text{ V}; V_{BE} = 0\text{ V}$   | -   | -     | -100  | nA            |                  |
| $I_{EBO}$   | emitter-base cut-off current            | $V_{EB} = -5\text{ V}; I_C = 0\text{ A}$   | -   | -     | -100  | nA            |                  |
| $h_{FE}$  | DC current gain                         | $V_{CE} = -2\text{ V}$   | [1] |       |       |               |                  |
|   |   | $I_C = -500\text{ mA}$   | 250 | 400   | -     |               |                  |
|   |   | $I_C = -1\text{ A}$  | 250 | 400   | -     |               |                  |
|   |   | $I_C = -2\text{ A}$  | 200 | 350   | -     |               |                  |
|   |   | $I_C = -4\text{ A}$  | 150 | 300   | -     |               |                  |
| $V_{CEsat}$   | collector-emitter saturation voltage    | $V_{CE} = -2\text{ V}$   | [1] |       |       |               |                  |
|   |   | $I_C = -1\text{ A}; I_B = -50\text{ mA}$   | -   | -45   | -68   | mV            |                  |
|   |   | $I_C = -1\text{ A}; I_B = -10\text{ mA}$   | -   | -70   | -115  | mV            |                  |
|   |   | $I_C = -2\text{ A}; I_B = -40\text{ mA}$   | -   | -100  | -150  | mV            |                  |
|   |   | $I_C = -4\text{ A}; I_B = -200\text{ mA}$  | -   | -150  | -225  | mV            |                  |
|   |   | $I_C = -4\text{ A}; I_B = -40\text{ mA}$   | -   | -250  | -375  | mV            |                  |
| $R_{CEsat}$   | collector-emitter saturation resistance | $I_C = -5\text{ A}; I_B = -500\text{ mA}$  | [1] | -     | 36    | 54            | $\text{m}\Omega$ |
|   |   |  |     |       |       |               |                  |
| $V_{BEsat}$   | base-emitter saturation voltage         | $V_{CE} = -2\text{ V}$   | [1] |       |       |               |                  |
|   |   | $I_C = -1\text{ A}; I_B = -100\text{ mA}$  | -   | -0.85 | -1    | V             |                  |
|   |   | $I_C = -4\text{ A}; I_B = -400\text{ mA}$  | -   | -1    | -1.2  | V             |                  |
| $V_{BEon}$  | base-emitter turn-on voltage            | $V_{CE} = -2\text{ V}; I_C = -2\text{ A}$  | [1] | -     | -0.76 | -0.85         | V                |
| $t_d$   | delay time                              | $V_{CC} = -12.5\text{ V}; I_C = -1\text{ A}; I_{Bon} = -0.05\text{ A}; I_{Boff} = 0.05\text{ A}$ | -   | 40    | -     | ns            |                  |
| $t_r$   | rise time                               |  | -   | 55    | -     | ns            |                  |
| $t_{on}$  | turn-on time                            |  | -   | 95    | -     | ns            |                  |
| $t_s$   | storage time                            |  | -   | 340   | -     | ns            |                  |
| $t_f$   | fall time                               |  | -   | 85    | -     | ns            |                  |
| $t_{off}$   | turn-off time                           |  | -   | 425   | -     | ns            |                  |
| $f_T$   | transition frequency                    | $V_{CE} = -10\text{ V}; I_C = -100\text{ mA}; f = 100\text{ MHz}$                                | -   | 105   | -     | MHz           |                  |
| $C_c$   | collector capacitance                   | $V_{CB} = -10\text{ V}; I_E = I_C = 0\text{ A}; f = 1\text{ MHz}$                                | -   | 95    | -     | pF            |                  |

[1] Pulse test:  $t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02$ .



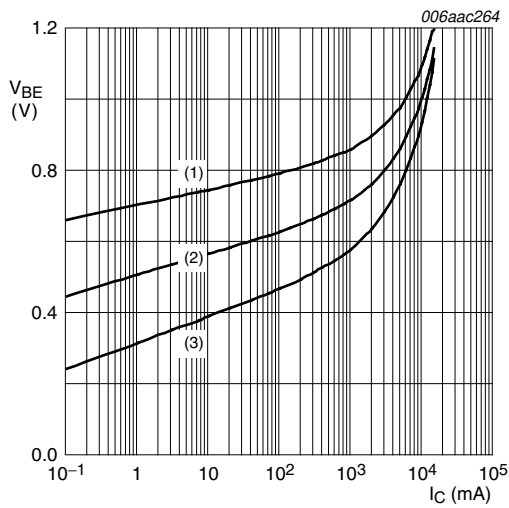
$V_{CE} = 2\text{ V}$   
 (1)  $T_{amb} = 100\text{ }^{\circ}\text{C}$   
 (2)  $T_{amb} = 25\text{ }^{\circ}\text{C}$   
 (3)  $T_{amb} = -55\text{ }^{\circ}\text{C}$

**Fig 5. TR1 (NPN): DC current gain as a function of collector current; typical values**



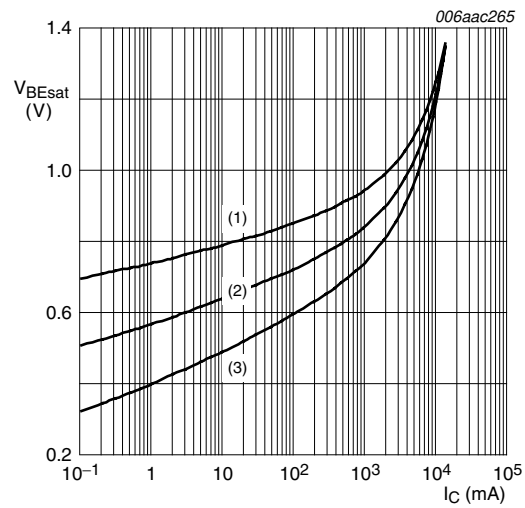
$T_{amb} = 25\text{ }^{\circ}\text{C}$

**Fig 6. TR1 (NPN): Collector current as a function of collector-emitter voltage; typical values**



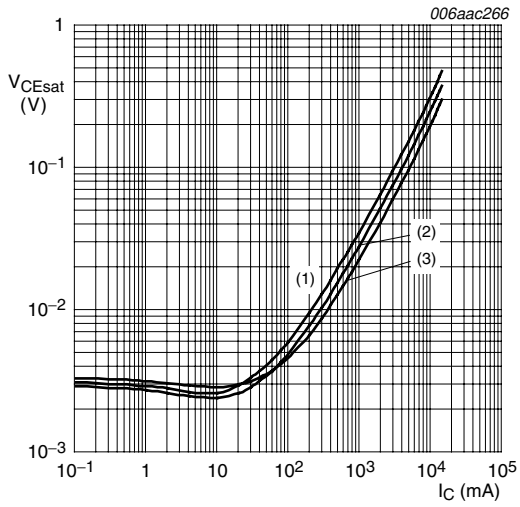
$V_{CE} = 2\text{ V}$   
 (1)  $T_{amb} = -55\text{ }^{\circ}\text{C}$   
 (2)  $T_{amb} = 25\text{ }^{\circ}\text{C}$   
 (3)  $T_{amb} = 100\text{ }^{\circ}\text{C}$

**Fig 7. TR1 (NPN): Base-emitter voltage as a function of collector current; typical values**



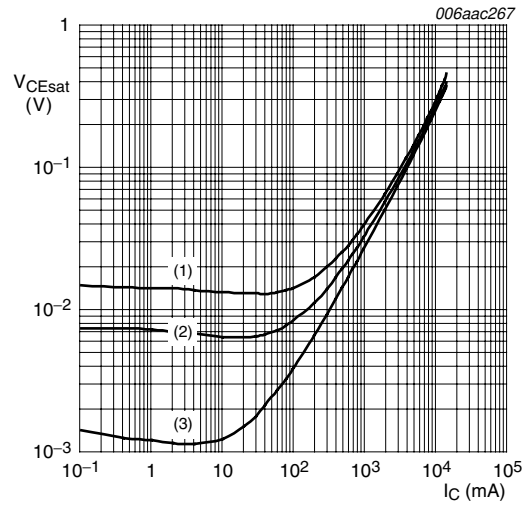
$I_C/I_B = 20$   
 (1)  $T_{amb} = -55\text{ }^{\circ}\text{C}$   
 (2)  $T_{amb} = 25\text{ }^{\circ}\text{C}$   
 (3)  $T_{amb} = 100\text{ }^{\circ}\text{C}$

**Fig 8. TR1 (NPN): Base-emitter saturation voltage as a function of collector current; typical values**



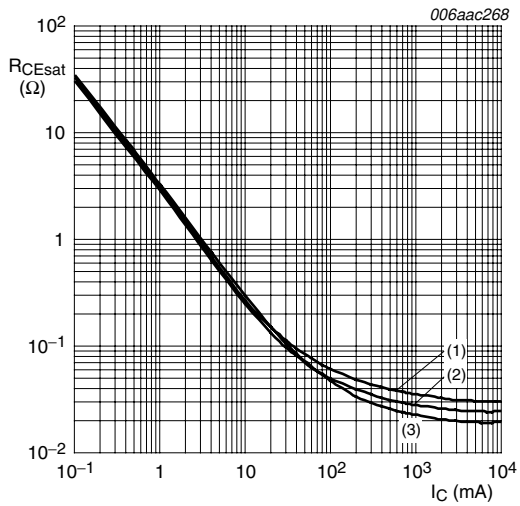
- $I_C/I_B = 20$
- (1)  $T_{amb} = 100\text{ °C}$
  - (2)  $T_{amb} = 25\text{ °C}$
  - (3)  $T_{amb} = -55\text{ °C}$

**Fig 9. TR1 (NPN): Collector-emitter saturation voltage as a function of collector current; typical values**



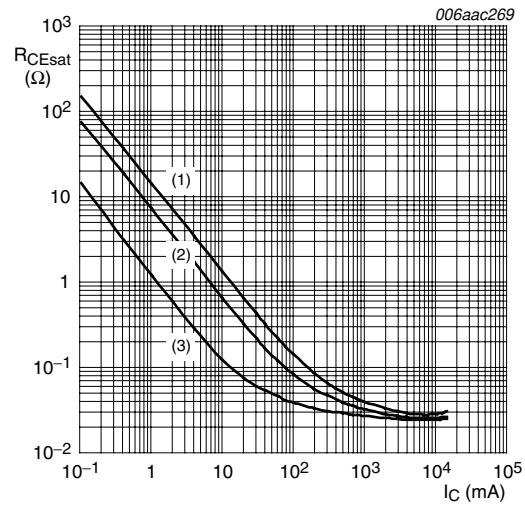
- $T_{amb} = 25\text{ °C}$
- (1)  $I_C/I_B = 100$
  - (2)  $I_C/I_B = 50$
  - (3)  $I_C/I_B = 10$

**Fig 10. TR1 (NPN): Collector-emitter saturation voltage as a function of collector current; typical values**



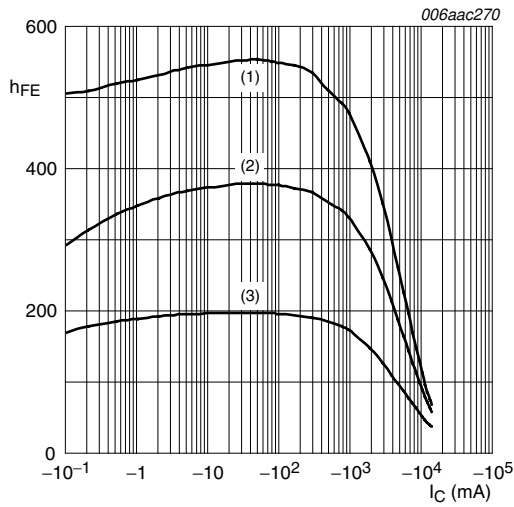
- $I_C/I_B = 20$
- (1)  $T_{amb} = 100\text{ °C}$
  - (2)  $T_{amb} = 25\text{ °C}$
  - (3)  $T_{amb} = -55\text{ °C}$

**Fig 11. TR1 (NPN): Collector-emitter saturation resistance as a function of collector current; typical values**



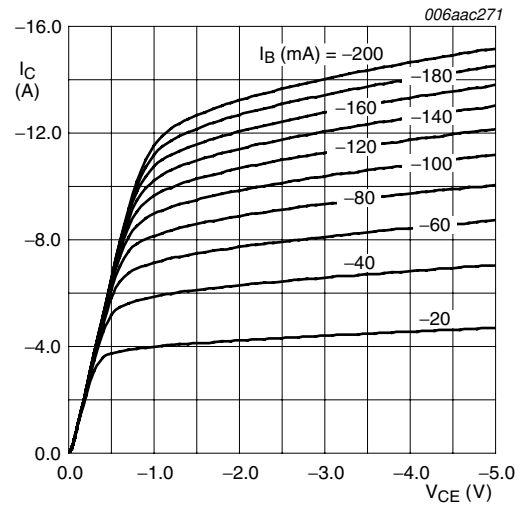
- $T_{amb} = 25\text{ °C}$
- (1)  $I_C/I_B = 100$
  - (2)  $I_C/I_B = 50$
  - (3)  $I_C/I_B = 10$

**Fig 12. TR1 (NPN): Collector-emitter saturation resistance as a function of collector current; typical values**



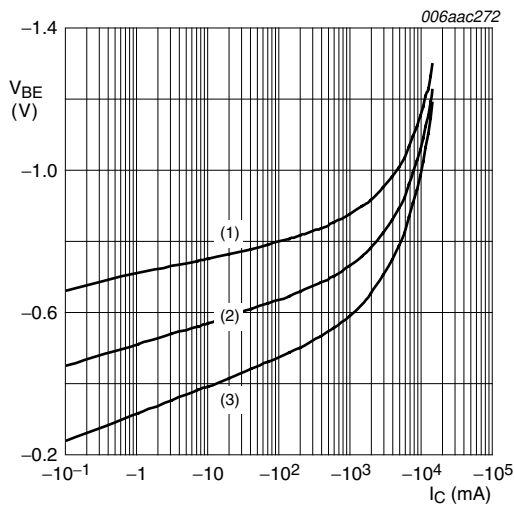
$V_{CE} = -2\text{ V}$   
 (1)  $T_{amb} = 100\text{ }^{\circ}\text{C}$   
 (2)  $T_{amb} = 25\text{ }^{\circ}\text{C}$   
 (3)  $T_{amb} = -55\text{ }^{\circ}\text{C}$

**Fig 13. TR2 (PNP): DC current gain as a function of collector current; typical values**



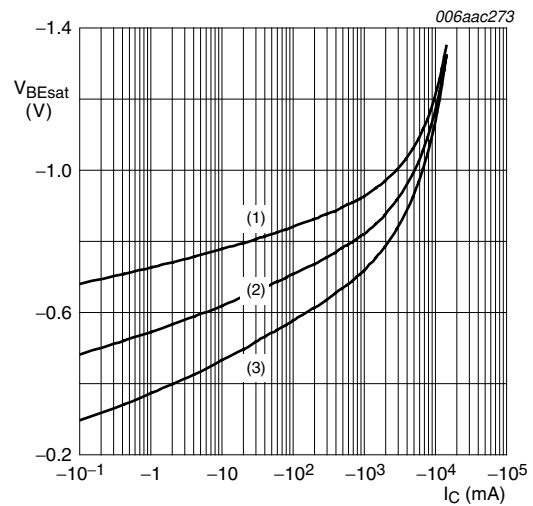
$T_{amb} = 25\text{ }^{\circ}\text{C}$

**Fig 14. TR2 (PNP): Collector current as a function of collector-emitter voltage; typical values**



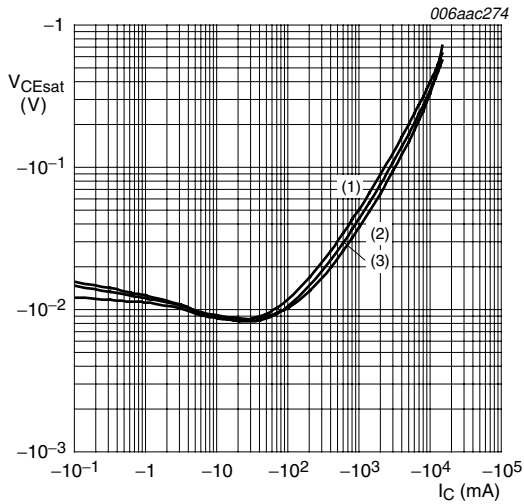
$V_{CE} = -2\text{ V}$   
 (1)  $T_{amb} = -55\text{ }^{\circ}\text{C}$   
 (2)  $T_{amb} = 25\text{ }^{\circ}\text{C}$   
 (3)  $T_{amb} = 100\text{ }^{\circ}\text{C}$

**Fig 15. TR2 (PNP): Base-emitter voltage as a function of collector current; typical values**



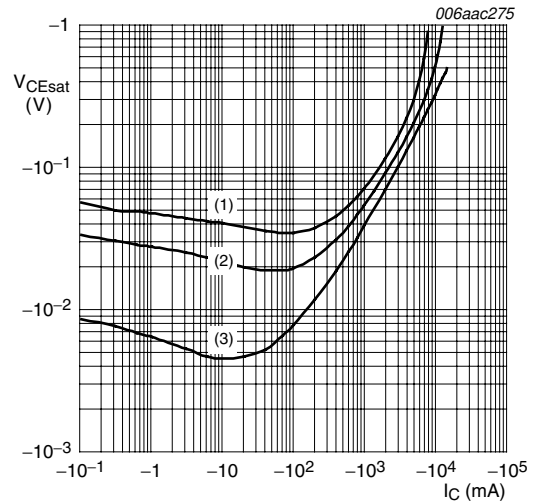
$I_C/I_B = 20$   
 (1)  $T_{amb} = -55\text{ }^{\circ}\text{C}$   
 (2)  $T_{amb} = 25\text{ }^{\circ}\text{C}$   
 (3)  $T_{amb} = 100\text{ }^{\circ}\text{C}$

**Fig 16. TR2 (PNP): Base-emitter saturation voltage as a function of collector current; typical values**



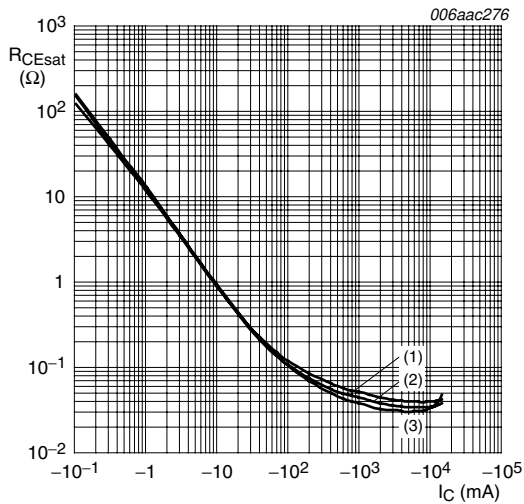
- $I_C/I_B = 20$
- (1)  $T_{amb} = 100\text{ °C}$
  - (2)  $T_{amb} = 25\text{ °C}$
  - (3)  $T_{amb} = -55\text{ °C}$

**Fig 17. TR2 (PNP): Collector-emitter saturation voltage as a function of collector current; typical values**



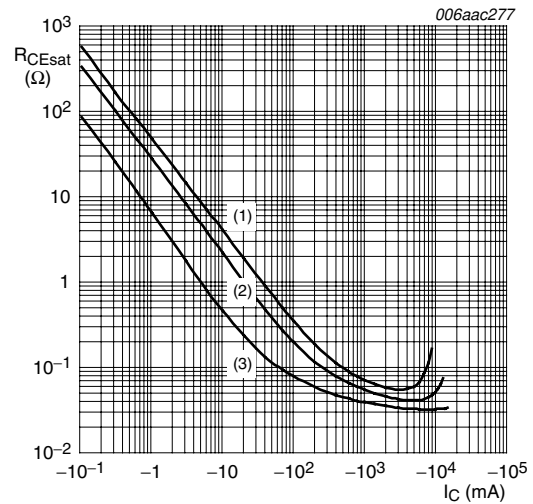
- $T_{amb} = 25\text{ °C}$
- (1)  $I_C/I_B = 100$
  - (2)  $I_C/I_B = 50$
  - (3)  $I_C/I_B = 10$

**Fig 18. TR2 (PNP): Collector-emitter saturation voltage as a function of collector current; typical values**



- $I_C/I_B = 20$
- (1)  $T_{amb} = 100\text{ °C}$
  - (2)  $T_{amb} = 25\text{ °C}$
  - (3)  $T_{amb} = -55\text{ °C}$

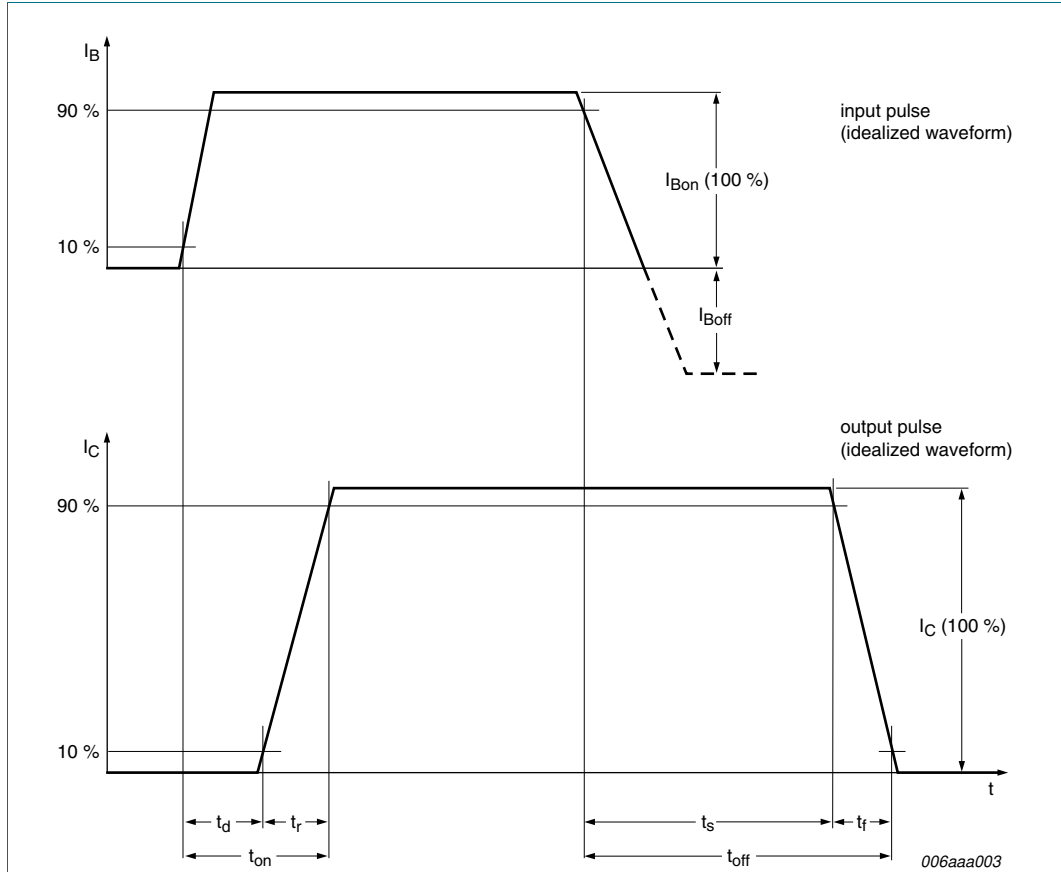
**Fig 19. TR2 (PNP): Collector-emitter saturation resistance as a function of collector current; typical values**



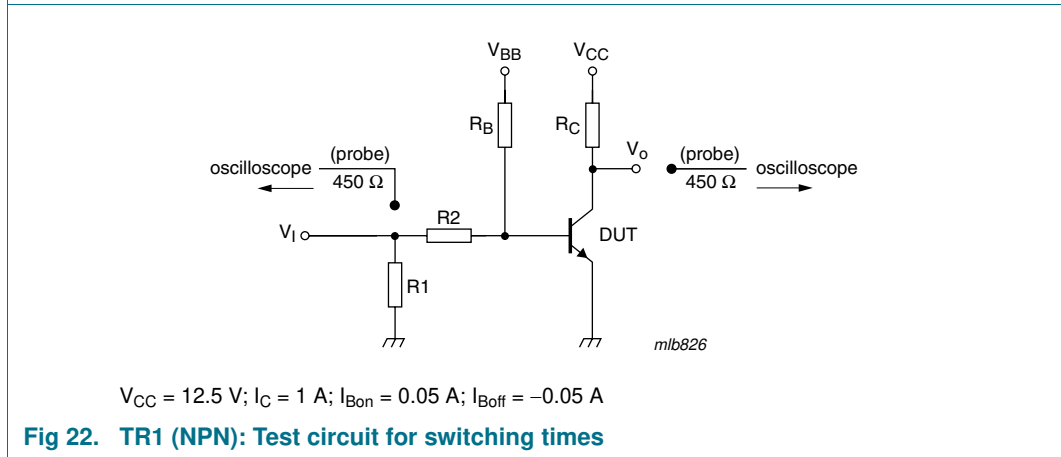
- $T_{amb} = 25\text{ °C}$
- (1)  $I_C/I_B = 100$
  - (2)  $I_C/I_B = 50$
  - (3)  $I_C/I_B = 10$

**Fig 20. TR2 (PNP): Collector-emitter saturation resistance as a function of collector current; typical values**

**8. Test information**



**Fig 21. TR1 (NPN): BISS transistor switching time definition**



**Fig 22. TR1 (NPN): Test circuit for switching times**

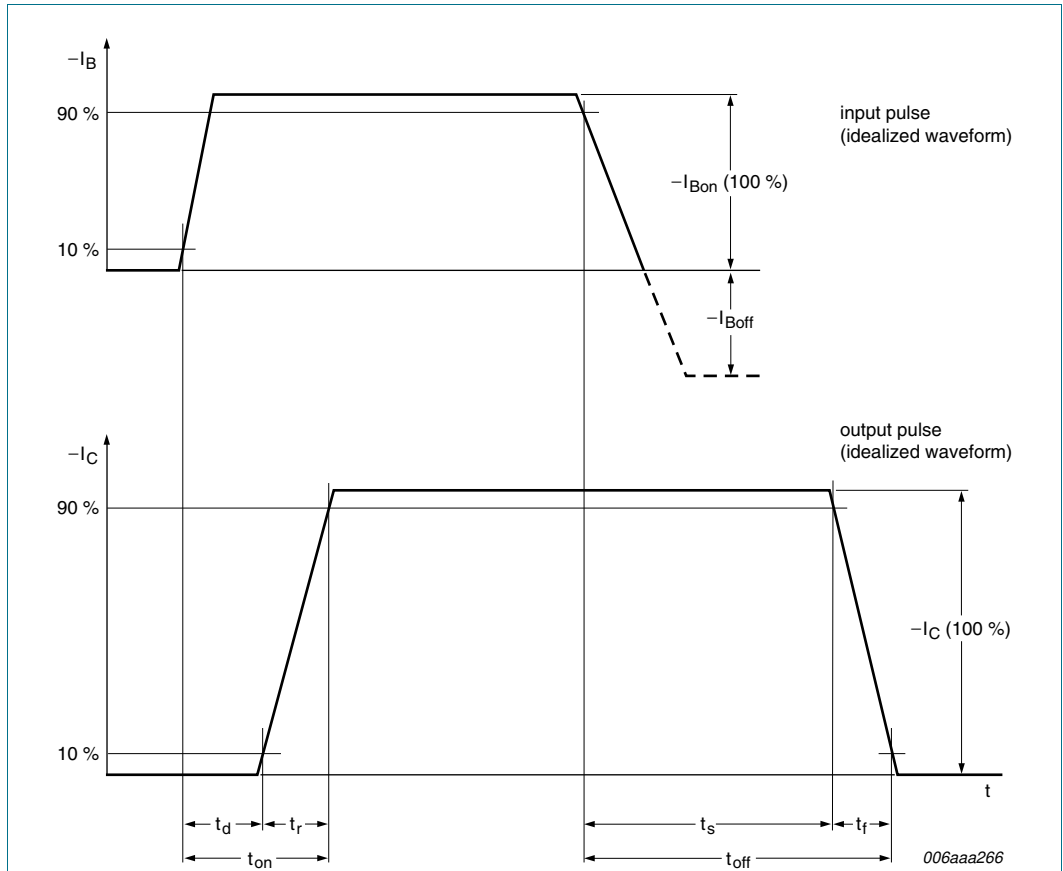


Fig 23. TR2 (PNP): BISS transistor switching time definition

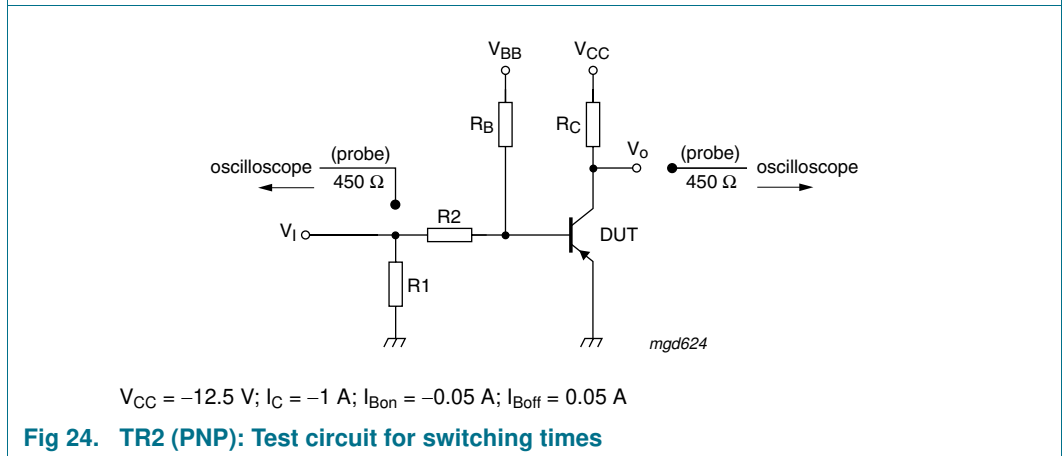
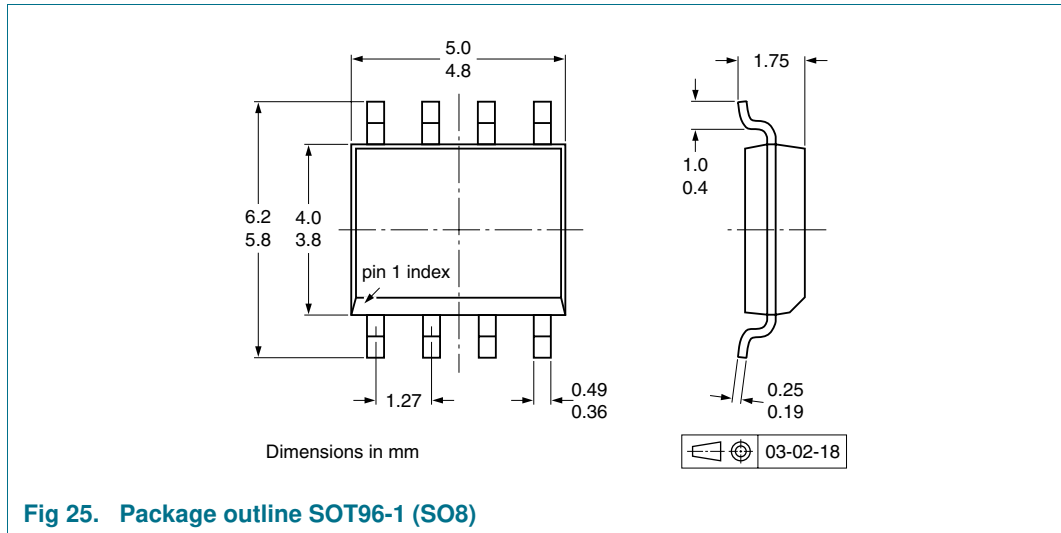


Fig 24. TR2 (PNP): Test circuit for switching times



## 9. Package outline



## 10. Packing information

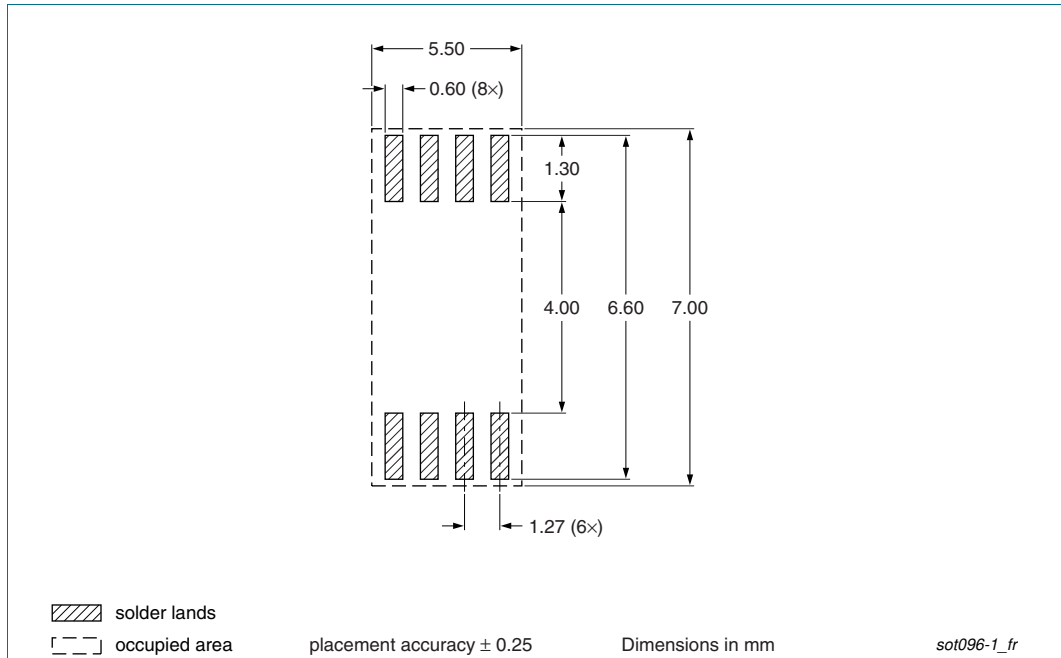
**Table 9. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

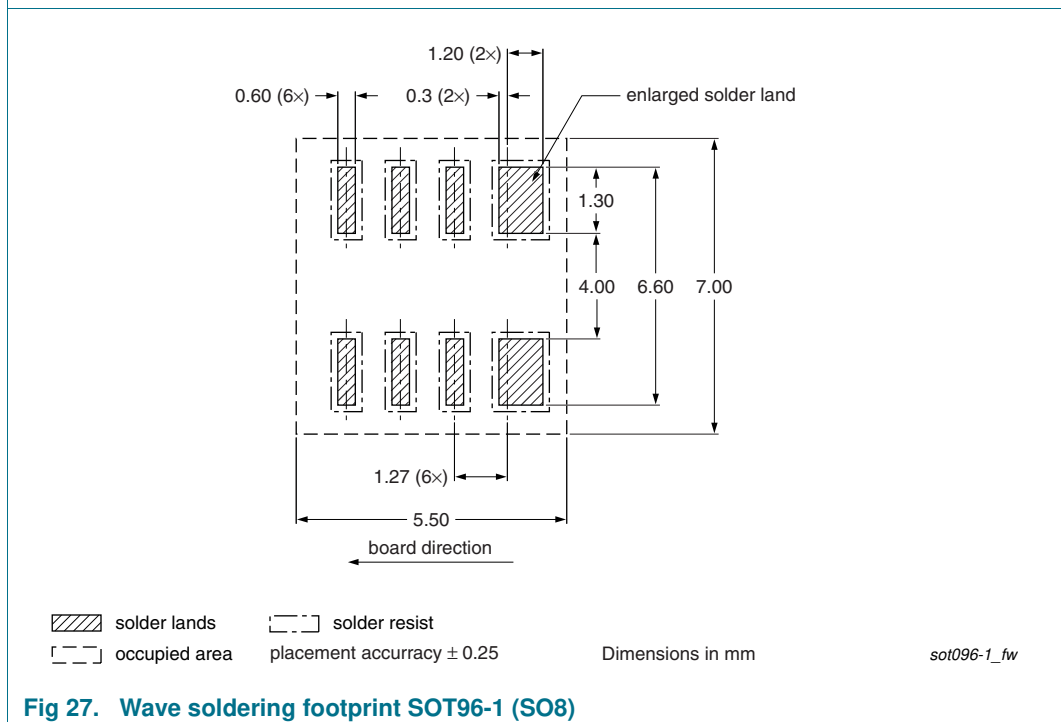
| Type number | Package | Description                     | Packing quantity |      |
|-------------|---------|---------------------------------|------------------|------|
|             |         |                                 | 1000             | 2500 |
| PBSS4021SPN | SOT96-1 | 8 mm pitch, 12 mm tape and reel | -115             | -118 |

[1] For further information and the availability of packing methods, see [Section 14](#).

## 11. Soldering



**Fig 26. Reflow soldering footprint SOT96-1 (SO8)**



**Fig 27. Wave soldering footprint SOT96-1 (SO8)**

## 12. Revision history

Table 10. Revision history

| Document ID     | Release date  | Data sheet status  | Change notice | Supersedes      |
|-----------------|---|--------------------|---------------|-----------------|
| PBSS4021SPN v.2 | 20101013  | Product data sheet | -             | PBSS4021SPN v.1 |
| Modifications:  | • <a href="#">Figure 1 "Per device: Power derating curves"</a> : updated. |                    |               |                 |
| PBSS4021SPN v.1 | 20100714  | Product data sheet | -             | -               |

## 13. Legal information

### 13.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition  |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)

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